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32-Channel Serial to Parallel Converter With High Voltage Push-Pull Outputs

Features

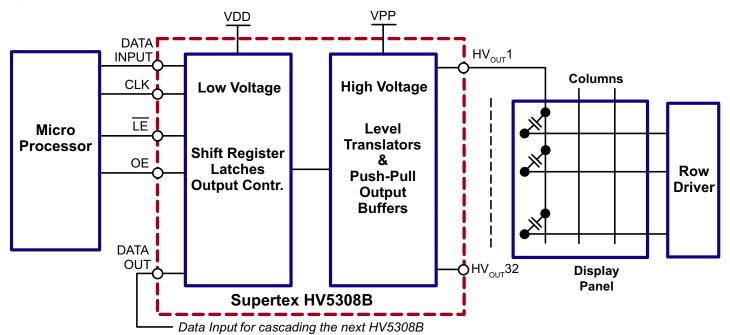
- Processed with HVCMOS® technology
- Low power level shifting
- Source/sink current minimum 20mA
- Shift register speed 8.0MHz
- Latched data outputs
- CMOS compatible inputs
- Forward and reverse shifting options
- Diode to VPP allows efficient power recovery

General Description

The HV5308B is a low voltage serial to high voltage parallel converter with push-pull outputs. This device has been designed for use as a driver for AC-electroluminescent displays. It can also be used in any application requiring multiple output high voltage current sourcing and sinking capabilities, such as driving plasma panels, vacuum fluorescent, or large matrix LCD displays.

The HV5308B consists of a 32-bit shift register, 32 latches, and control logic to enable outputs. Q1 is connected to the first stage of the shift register through the Output Enable logic. Data is shifted through the shift register on the low to high transition of the clock. When viewed from the top of the package, the HV5308B shifts in the clockwise direction. A data output buffer is provided for cascading devices. This output reflects the current status of the last bit of the shift register (32). Operation of the shift register is not affected by the $\overline{\text{LE}}$ (latch enable) or the OE (output enable) inputs. Transfer of data from the shift register to the latch occurs when the $\overline{\text{LE}}$ input is high. The data in the latch is retained when $\overline{\text{LE}}$ is low.

Typical Application Circuit



Ordering Information

	Package Options						
Device	44-Lead Quad Cerpac .650x.650in body .190in height (max) .050in pitch	44-Lead PQFP 10.00x10.00mm body 2.35mm height (max) 0.80mm pitch	44-Lead PLCC .653x.653in body .180in height (max) .050in pitch				
HV5308B	HV5308DJ-B*	HV5308PG-B-G	HV5308PJ-B-G				





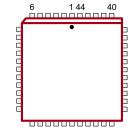
Absolute Maximum Ratings

	J -
Parameter	Value
Supply voltage, V _{DD}	-0.5V to +16V
Supply voltage, V _{PP}	-0.5V to +90V
Logic input levels	-0.5V to V _{DD} +0.5V
Ground current ¹	1.5A
Continuous total power dissipation ² Plastic Ceramic	1200mW 1500mW
Operating temperature range Plastic Ceramic	-40°C to +85°C -55°C to +125°C
Storage temperature range	-65°C to +150°C

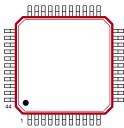
Absolute Maximum Ratings are those values beyond which damage to the device may occur. Functional operation under these conditions is not implied. Continuous operation of the device at the absolute rating level may affect device reliability. All voltages are referenced to device ground.

- Duty cycle is limited by the total power dissipated in the package. 1.
- For operation above 25°C ambient derate linearly to maximum operating temperature at 20mW/°C for plastic and at 15mW/°C for ceramic.

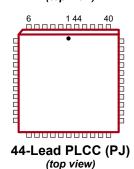
Pin Configurations



44-Lead Quad Cerpac (DJ) (top view)



44-Lead PQFP (PG) (top view)



Product Marking







(PJ)

Packages may or may not include the following marks: Si or



G indicates package is RoHS compliant ('Green').

Hi-Rel process flow available.

Recommended Operating Conditions (over -40°C to 85°C for plastic and -55°C to 125°C for ceramic)

Sym	Parameter	Min	Max	Units
V _{DD}	Logic voltage supply	10.8	13.2	V
V _{PP}	High voltage supply	8.0	V	
V _{IH}	Input high voltage	V _{DD} - 2.0	V _{DD}	V
V _{IL}	Input low voltage	0	2.0	V
f _{CLK}	Clock frequency	0	8.0	MHz

Power-Up Sequence

Power-up sequence should be the following:

- 1. Connect ground
- 2. Apply V_{DD}
- 3. Set all inputs (Data, CLK, \overline{LE} , etc.) to a known state
- 4. Apply V
- 5. The V_{PP} should not fall below V_{DD} or float during operation.

Power-down sequence should be the reverse of the above.

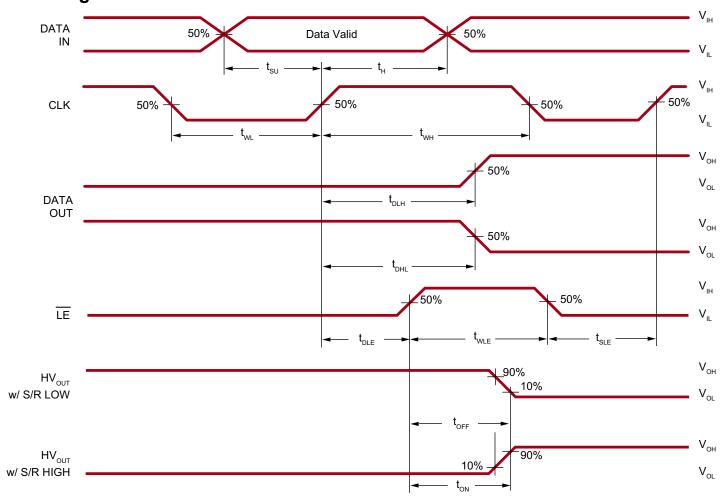
Electrical Characteristics $(V_{PP} = 60V, V_{DD} = 12V, T_A = 25^{\circ}C)$ **DC Characteristics**

		Min	1		1
Sym	Parameter		Max	Units	Conditions
l _{PP}	V _{PP} supply current	-	0.5	mA	HV _{OUTPUTS} high to low
I _{DDQ}	I _{DD} supply current (quiescent)	-	100	μΑ	All inputs = V _{DD} or GND
I _{DD}	I _{DD} supply current (operating)	-	15	mA	$V_{DD} = V_{DD} \text{ max}, f_{CLK} = 8.0 \text{MHz}$
V _{OH} (data)	Shift register output voltage	10.5	-	V	I _o = -100μA
V _{OL} (data)	Shift register output voltage	-	1.0	V	I _o = 100μA
I _{IH}	Current leakage, any input	-	1.0	μΑ	$V_{IN} = V_{DD}$
I _{IL}	Current leakage, any input	-	-1.0	μΑ	V _{IN} = 0
V _{oc}	HV output clamp diode voltage	-	-1.5	V	I _{OL} = -100mA
V _{OH}	HV output when sourcing	52	-	V	I _{OH} = -20mA, -40 to 85°C
V _{oL}	HV output when sinking	-	8.0	V	I _{OL} = 20mA, -40 to 85°C
V _{OH}	HV output when sourcing	52	-	V	I _{OH} = -15mA, -55 to 125°C
V _{oL}	HV output when sinking	-	8.0	V	I _{oL} = 15mA, -55 to 125°C

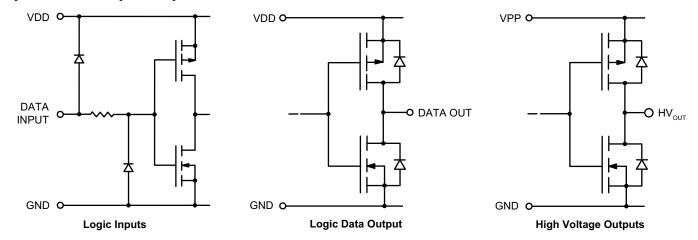
AC Characteristics

Sym	Parameter	Min	Max	Units	Conditions
f _{CLK}	Clock frequency	-	8.0	MHz	
t _{wL} or t _{wH}	Clock width, HIGH or LOW	62	-	ns	
t _{su}	Setup time before CLK rises	25	-	ns	
t _H	Hold time after CLK rises	10	-	ns	
t _{DLH} (Data)	Data output delay after L to H CLK	-	110	ns	C _L = 15pF
t _{DHL} (Data)	Data output delay after H to L CLK	-	110	ns	C _L = 15pF
t _{DLE}	LE delay after L to H CLK	50	-	ns	
t _{wle}	Width of LE pulse	50	-	ns	
t _{SLE}	LE setup time before L to H CLK	50	-	ns	
t _{on}	Delay from \overline{LE} to HV_{OUT} , L to H	-	500	ns	
t _{OFF}	Delay from \overline{LE} to HV_{OUT} , H to L	-	500	ns	

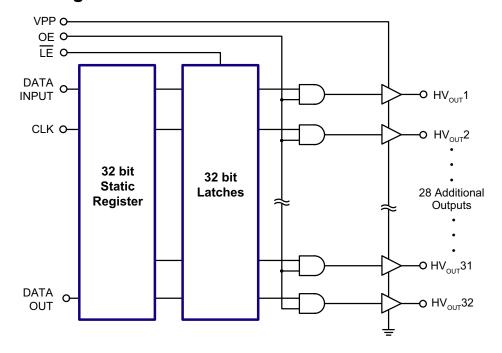
Switching Waveforms



Input and Output Equivalent Circuits



Functional Block Diagram



Function Tables

DATA IN	CLK*	DATA OUT
Н	<u>_</u>	Н
L		L
X	No <u></u>	No change

Note:

*
$$\mathbf{L} = LOW - to - HIGH transition$$

H = High L = Low

X = Don't Care

DATA IN	<u>LE</u>	OE	HV OUT
Х	X	L	All HV _{OUT} = LOW
Х	L	Н	Previous latched data
Н	Н	Н	Н
L	Н	Н	L

44-Lead PQFP Pin Assignment (PG)

1	Pin#	Function	Description
3	1	HV _{OUT} 22	
4 HV _{our} 19 5 HV _{our} 18 6 HV _{our} 17 7 HV _{our} 16 8 HV _{our} 14 10 HV _{our} 13 11 HV _{our} 12 12 HV _{our} 11 13 HV _{our} 10 14 HV _{our} 10 14 HV _{our} 09 15 HV _{our} 8 16 HV _{our} 7 17 HV _{our} 8 16 HV _{our} 7 17 HV _{our} 8 18 HV _{our} 9 15 HV _{our} 8 16 HV _{our} 7 17 HV _{our} 8 18 HV _{our} 9 19 HV _{our} 1 20 HV _{our} 1 21 HV _{our} 1 22 HV _{our} 1 23 DATA OUT Serial data output. Data output for cascading to the data input of the next device. 24 N/C 25 N/C 26 CLK Data shift register clock Input are shifted into the shift register on the positive edge of the clock. Logic and high voltage ground	2	HV _{OUT} 21	
5 HV _{our} 18 6 HV _{our} 17 7 HV _{our} 16 8 HV _{our} 15 9 HV _{our} 14 10 HV _{our} 12 11 HV _{our} 12 12 HV _{our} 11 13 HV _{our} 10 14 HV _{our} 9 15 HV _{our} 8 16 HV _{our} 7 17 HV _{our} 8 16 HV _{our} 7 17 HV _{our} 8 18 HV _{our} 5 19 HV _{our} 1 20 HV _{our} 7 21 HV _{our} 1 22 HV _{our} 1 23 DATA OUT Data output for cascading to the data input of the next device. 24 N/C 25 N/C Data shift register clock Input are shifted into the shift register on the positive edge of the clock.	3	HV _{OUT} 20	
6 HV _{our} 17 7 HV _{our} 16 8 HV _{our} 15 9 HV _{our} 14 10 HV _{our} 12 11 HV _{our} 12 12 HV _{our} 10 13 HV _{our} 10 14 HV _{our} 9 15 HV _{our} 9 15 HV _{our} 8 16 HV _{our} 7 17 HV _{our} 8 18 HV _{our} 15 19 HV _{our} 8 20 HV _{our} 1 21 HV _{our} 8 21 HV _{our} 1 22 HV _{our} 1 23 DATA OUT Data output for cascading to the data input of the next device. 24 25 N/C Data shift register clock Input are shifted into the shift register on the positive edge of the clock.	4	HV _{out} 19	
7	5	HV _{out} 18	
8	6	HV _{out} 17	
9 HV _{our} 14 10 HV _{our} 13 11 HV _{our} 12 12 HV _{our} 11 13 HV _{our} 10 14 HV _{our} 9 15 HV _{our} 8 16 HV _{our} 5 19 HV _{our} 6 18 HV _{our} 5 20 HV _{our} 1 21 HV _{our} 1 22 HV _{our} 1 DATA OUT Serial data output. Data output for cascading to the data input of the next device. No connect. CLK Data shift register clock Input are shifted into the shift register on the positive edge of the clock. Logic and high voltage ground	7	HV _{out} 16	
10	8	HV _{OUT} 15	
High voltage outputs. Hyour12 HVour11 HYour10 HVour10 HVour9 HS HVour6 HVour6 HVour6 HVour9 HVour6 HVour12 Data output for cascading to the data input of the next device. Page 12 N/C Data shift register clock Input are shifted into the shift register on the positive edge of the clock. Right voltage outputs. High voltage outputs. High voltage outputs, which, depending on controlling low voltage data, can drive loads either to GND, or to V _{pp} rail levels. High voltage outputs, which, depending on controlling low voltage data, can drive loads either to GND, or to V _{pp} rail levels. High voltage outputs, which, depending on controlling low voltage data, can drive loads either to GND, or to V _{pp} rail levels. High voltage outputs, which, depending on controlling low voltage data, can drive loads either to GND, or to V _{pp} rail levels. High voltage outputs. High voltage outputs. High voltage outputs, which, depending on controlling low voltage data, can drive loads either to GND, or to V _{pp} rail levels.	9	HV _{OUT} 14	
11 HV _{our} 12 12 HV _{our} 11 13 HV _{our} 10 14 HV _{our} 9 15 HV _{our} 8 16 HV _{our} 7 17 HV _{our} 8 18 HV _{our} 5 19 HV _{our} 2 20 HV _{our} 3 21 HV _{our} 2 22 HV _{our} 1 23 DATA OUT Serial data output. Data output for cascading to the data input of the next device. 24 25 N/C 27 CLK Data shift register clock Input are shifted into the shift register on the positive edge of the clock. 28 GND Logic and high voltage ground	10	HV _{out} 13	High voltage outputs
13 HV _{out} 10 14 HV _{out} 9 15 HV _{out} 7 17 HV _{out} 6 18 HV _{out} 5 19 HV _{out} 3 21 HV _{out} 1 22 HV _{out} 1 23 DATA OUT Serial data output. Data output for cascading to the data input of the next device. 24 25 N/C 27 CLK Data shift register clock Input are shifted into the shift register on the positive edge of the clock. 28 GND Logic and high voltage ground	11	HV _{OUT} 12	nigit voitage outputs.
13 HV _{our} 10 14 HV _{our} 9 15 HV _{our} 8 16 HV _{our} 7 17 HV _{our} 6 18 HV _{our} 5 19 HV _{our} 4 20 HV _{our} 3 21 HV _{our} 1 22 HV _{our} 1 23 DATA OUT Serial data output. Data output for cascading to the data input of the next device. 24 25 N/C No connect. 26 Data shift register clock Input are shifted into the shift register on the positive edge of the clock. 28 GND Logic and high voltage ground	12	HV _{OUT} 11	
15	13	HV _{OUT} 10	can unive loads either to GND, or to v _{PP} fail levels.
16 HV _{our} 7 17 HV _{our} 6 18 HV _{our} 5 19 HV _{our} 3 21 HV _{our} 2 22 HV _{our} 1 23 DATA OUT Serial data output. Data output for cascading to the data input of the next device. No connect. CLK Data shift register clock Input are shifted into the shift register on the positive edge of the clock. Logic and high voltage ground	14	HV _{out} 9	
17 HV _{our} 6 18 HV _{our} 5 19 HV _{our} 4 20 HV _{our} 3 21 HV _{our} 2 22 HV _{our} 1 23 DATA OUT Serial data output. Data output for cascading to the data input of the next device. 24 25 N/C No connect. 26 Data shift register clock Input are shifted into the shift register on the positive edge of the clock. 28 GND Logic and high voltage ground	15	HV _{out} 8	
18 HV _{OUT} 5 19 HV _{OUT} 4 20 HV _{OUT} 3 21 HV _{OUT} 2 22 HV _{OUT} 1 23 DATA OUT Serial data output. Data output for cascading to the data input of the next device. 24 N/C No connect. 26 Data shift register clock 10 Input are shifted into the shift register on the positive edge of the clock. 28 GND Logic and high voltage ground	16	HV _{out} 7	
19 HV _{our} 4 20 HV _{our} 3 21 HV _{our} 2 22 HV _{our} 1 23 DATA OUT Serial data output. Data output for cascading to the data input of the next device. 24 25 N/C No connect. 26 Data shift register clock Input are shifted into the shift register on the positive edge of the clock. 28 GND Logic and high voltage ground	17	HV _{out} 6	
20 HV _{out} 3 21 HV _{out} 2 22 HV _{out} 1 23 DATA OUT Data output for cascading to the data input of the next device. 24 25 N/C No connect. 26 Data shift register clock Input are shifted into the shift register on the positive edge of the clock. 28 GND Logic and high voltage ground	18	HV _{out} 5	
21 HV _{out} 2 22 HV _{out} 1 23 DATA OUT Serial data output. Data output for cascading to the data input of the next device. N/C No connect. Data shift register clock CLK Input are shifted into the shift register on the positive edge of the clock. Logic and high voltage ground	19	HV _{out} 4	
22 HV _{OUT} 1 23 DATA OUT Serial data output. Data output for cascading to the data input of the next device. 24 25 N/C No connect. 26 Data shift register clock Input are shifted into the shift register on the positive edge of the clock. 28 GND Logic and high voltage ground	20	HV _{out} 3	
Serial data output. Data output for cascading to the data input of the next device. No connect. Data shift register clock CLK Input are shifted into the shift register on the positive edge of the clock. CRA CNA CNA COMB Data output for cascading to the data input of the next device. No connect. Data shift register clock Input are shifted into the shift register on the positive edge of the clock. Logic and high voltage ground	21	HV _{out} 2	
Data output for cascading to the data input of the next device. No connect. Data shift register clock CLK Input are shifted into the shift register on the positive edge of the clock. CRU CNO CONNECT. Data shift register clock Input are shifted into the shift register on the positive edge of the clock. Data shift register on the positive edge of the clock.	22	HV _{out} 1	
Data output for cascading to the data input of the next device. N/C No connect. Data shift register clock CLK Input are shifted into the shift register on the positive edge of the clock. CND Logic and high voltage ground	22	DATA OUT	Serial data output.
24 25 N/C No connect. 26 Data shift register clock CLK Input are shifted into the shift register on the positive edge of the clock. 28 GND Logic and high voltage ground	23	DAIAOUI	Data output for cascading to the data input of the next device.
26 27 CLK Data shift register clock Input are shifted into the shift register on the positive edge of the clock. 28 GND Logic and high voltage ground	24		
Data shift register clock CLK Input are shifted into the shift register on the positive edge of the clock. CND Logic and high voltage ground	25	N/C	No connect.
27 CLK Input are shifted into the shift register on the positive edge of the clock. 28 GND Logic and high voltage ground	26		
Input are shifted into the shift register on the positive edge of the clock. 28 GND Logic and high voltage ground		0116	Data shift register clock
28 GND Logic and high voltage ground	27	CLK	Input are shifted into the shift register on the positive edge of the clock.
	28	GND	
	29		
30 VDD Low voltage logic power rail.			

44-Lead PQFP Pin Assignment (PG)

Pin#	Function	Description
31	ĪĒ	Latch enable input. When LE is HIGH, shift register data is transferred into a data latch. When LE is LOW, data is latched, and new data can be clocked into the shift register.
32	DATA IN	Serial data input. Data needs to be present before each rising edge of the clock.
33	OE	Output enable input. When OE is LOW, all HV outputs are forced into a LOW state, regardless of data in each channel. When OE is HIGH, all HV outputs reflect data latched.
34	N/C	No connect.
35	HV _{OUT} 32	
36	HV _{OUT} 31	
37	HV _{OUT} 30	
38	HV _{OUT} 29	Llieb velte se evitevite
39	HV _{OUT} 28	High voltage outputs.
40	HV _{OUT} 27	High voltage push-pull outputs, which, depending on controlling low voltage data,
41	HV _{OUT} 26	can drive loads either to GND, or to V _{PP} rail levels.
42	HV _{OUT} 25	
43	HV _{OUT} 24	
44	HV _{out} 23	

44-Lead Quad Cerpac/PLCC Pin Assignment (DJ/PJ)

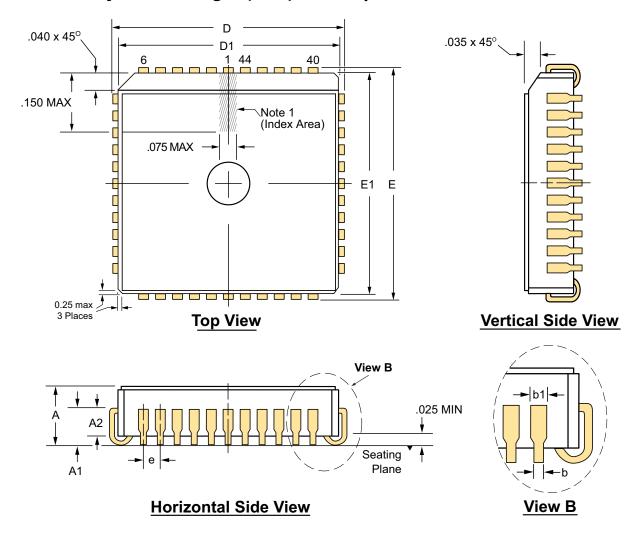
Pin#	Function	Description						
1	HV _{out} 17							
2	HV _{out} 16							
3	HV _{out} 15							
4	HV _{out} 14							
5	HV _{out} 13							
6	HV _{out} 12							
7	HV _{out} 11							
8	HV _{out} 10	High voltage outputs.						
9	HV _{OUT} 9	High voltage push-pull outputs, which, depending on controlling low voltage data,						
10	HV _{OUT} 8	can drive loads either to GND, or to V_{PP} rail levels.						
11	HV _{OUT} 7							
12	HV _{OUT} 6							
13	HV _{OUT} 5							
14	HV _{OUT} 4							
15	HV _{OUT} 3							
16	HV _{OUT} 2							
17	HV _{out} 1							
18	DATA OUT	Serial data output.						
10	DAIAGGI	Data output for cascading to the data input of the next device.						
19								
20	N/C	No connect.						
21								
		Data shift register clock						
22	CLK	Input are shifted into the shift register on the positive edge of the clock.						
23	GND	Logic and high voltage ground						
24	VPP	High voltage power rail.						
25	VDD	Low voltage logic power rail.						
		Latch enable input.						
26	ĪĒ	When LE is HIGH, shift register data is transferred into a data latch. When LE is LOW, data is latched, and new data can be clocked into the shift register.						
		Serial data input.						
27	DATA IN	Data needs to be present before each rising edge of the clock.						

44-Lead Quad Cerpac/PLCC Pin Assignment (DJ/PJ)

Pin#	Function	Description
28	OE	Output enable input. When OE is LOW, all HV outputs are forced into a LOW state, regardless of data in each channel. When OE is HIGH, all HV outputs reflect data latched.
29	N/C	No connect.
30	HV _{ουτ} 32	
31	HV _{ουτ} 31	
32	HV _{OUT} 30	
33	HV _{out} 29	
34	HV _{out} 28	
35	HV _{out} 27	
36	HV _{out} 26	High voltage outputs.
37	HV _{out} 25	High voltage push-pull outputs, which, depending on controlling low voltage data,
38	HV _{out} 24	can drive loads either to GND, or to $V_{\rm pp}$ rail levels.
39	HV _{OUT} 23	
40	HV _{out} 22	
41	HV _{out} 21	
42	HV _{out} 20	
43	HV _{OUT} 19	
44	HV _{out} 18	

44-Lead Quad Cerpac Package Outline (DJ)

.650x.650in body, .190in height (max), .050in pitch



Note:

 A Pin 1 identifier must be located in the index area indicated. The Pin 1 identifier can be: a molded mark/identifier; an embedded metal marker; or a printed indicator.

Symb	ol	Α	A1	A2	b	b1	D	D1	E	E1	е
. .	MIN	.155	.090	000	.017	.026	.685	.630	.685	.630	050
Dimension (inches)	NOM	.172	.100	.060 REF	.019	.029	.690	.650	.690	.650	.050 BSC
(inches)	MAX	.190	.120		.021	.032	.695	.665	.695	.665	ВОО

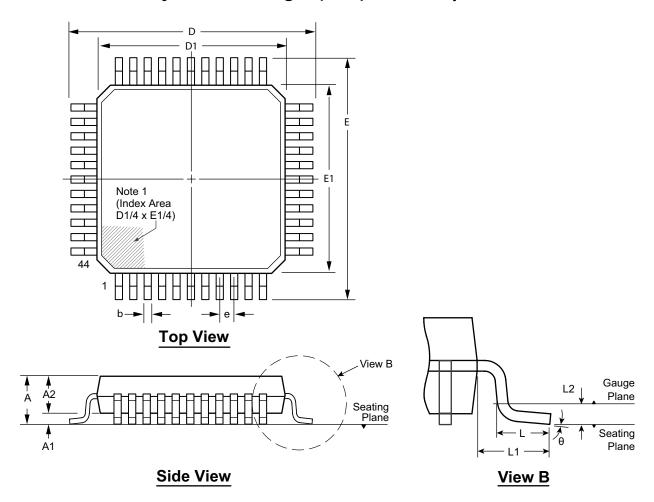
JEDEC Registration MO-087, Variation AB, Issue B, August, 1991.

Drawings not to scale.

Supertex Doc. #: DSPD-44CERPACDJ, Version D090808.

44-Lead PQFP Package Outline (PG)

10.00x10.00mm body, 2.35mm height (max), 0.80mm pitch



Note:

 A Pin 1 identifier must be located in the index area indicated. The Pin 1 identifier can be: a molded mark/identifier; an embedded metal marker; or a printed indicator.

Symbol		Α	A1	A2	b	D	D1	E	E1	е	L	L1	L2	θ
Dimension (mm)	MIN	1.95*	0.00	1.95	0.30	13.65*	9.80*	13.65*	9.80*	0.80 BSC	0.73	1.95 REF	0.25 BSC	0 º
	NOM	-	-	2.00	-	13.90	10.00	13.90	10.00		0.88			3.5°
	MAX	2.35	0.25	2.10	0.45	14.15*	10.20*	14.15*	10.20*		1.03			7 °

JEDEC Registration MO-112, Variation AA-2, Issue B, Sep.1995.

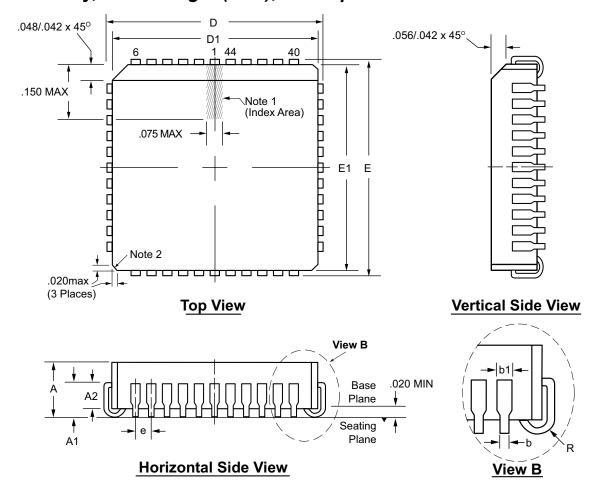
Drawings not to scale.

Supertex Doc. #: DSPD-44PQFPPG, Version C041309.

^{*} This dimension is not specified in the JEDEC drawing.

44-Lead PLCC Package Outline (PJ)

.653x.653in body, .180in height (max), .050in pitch



Notes:

- A Pin 1 identifier must be located in the index area indicated. The Pin 1 identifier can be: a molded mark/identifier; an embedded metal marker; or a printed indicator.
- 2. Actual shape of this feature may vary.

Symbol		Α	A1	A2	b	b1	D	D1	Ε	E1	е	R
Dimension (inches)	MIN	.165	.090	.062	.013	.026	.685	.650	.685	.650	.050 BSC	.025
	NOM	.172	.105	-	-	-	.690	.653	.690	.653		.035
	MAX	.180	.120	.083	.021	.036 [†]	.695	.656	.695	.656		.045

JEDEC Registration MS-018, Variation AC, Issue A, June, 1993.

† This dimension differs from the JEDEC drawing.

Drawings not to scale.

Supertex Doc. #: DSPD-44PLCCPJ, Version F031111.

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to http://www.supertex.com/packaging.html.)

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